



# **STIC Search Report**

## **EIC 3700**

**STIC Database Tracking Number: 109464**

**TO: Timothy Eley**  
**Location: cp2 11d06**  
**Art Unit: 3724**  
**Tuesday, December 02, 2003**

**Case Serial Number: 09/199198**

**From: Terry Solomon**  
**Location: EIC 3700**  
**CP2-2C08**  
**Phone: 305-5932**

**Terrance.solomon@uspto.gov**

### **Search Notes**

No litigation found.

Sources: **Lexis/Nexis and Questel-Orbit**

UNITED STATES PATENT AND TRADEMARK OFFICE GRANTED PATENT

**6142138**

November 7, 2000

High speed method of aligning cutting lines of a workpiece using patterns

**REISSUE:** January 23, 2002 - Reissue Application filed Ex. Gp.: 3723; Re. S.N. 10/053,377 (O.G. May 21, 2002)

**APPL-NO:** 199198 (09)

**FILED-DATE:** November 25, 1998

**GRANTED-DATE:** November 7, 2000

**LEGAL-REP:** Nixon Peabody LLP; Safran, David S.

**ENGLISH-ABST:**

Two imaging equipment are provided at a pair of cutting blade units, and the two imaging equipment image patterns at first positions in proximity to the center of a wafer at the same time. A controller drives drive mechanisms to align the wafer in such a way that current image patterns at the first positions can match with a reference pattern at the first positions. Then, the two imaging equipment are moved to positions for imaging patterns at second positions at the outer circumference of the wafer to image the patterns at the second positions. The controller drives the drive mechanisms to align the wafer in such a way that current image patterns at the second positions can match with a reference pattern at the second positions.

Segments: Abst, Appl-no, Cert-correction, Legal-rep, Legal-status, Lit-reex, Patno, Reexam-cert, Reexam-litigate, Reissue, Reissue-comment

Date/Time: Tuesday, December 2, 2003 - 8:43 AM EST

Selected file: PLUSPAT

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Comprehensive Worldwide Patents database

\*\* SS 1: Results 1

Query/Command : prt fu nonstop legalall

1 / 1 PLUSPAT - @QUESTEL-ORBIT - image  
PN - US6142138 A 20001107 [US6142138]  
TI - (A) High speed method of aligning cutting lines of a workpiece  
using patterns  
PA - (A) TOKYO SEIMITSU CO LTD (JP); KULICKE & SOFFA INVESTMENTS (US)  
PAO - Tokyo Seimitsu Company, Ltd., Tokyo [JP]  
Kulicke & Soffa Investments, Inc., Wilmington DE [US]  
IN - (A) AZUMA MASAYUKI (JP); SHIMODA HIROFUMI (JP)  
AP - US19919898 19981125 [1998US-0199198]  
PR - JP33054097 19971201 [1997JP-0330540]  
IC - (A) B28D-001/04  
EC - B23D-059/00B1  
B27B-031/06  
B28D-005/02C10  
PCL - ORIGINAL (O) : 125014000; CROSS-REFERENCE (X) : 083425200  
083471300 125013010 451190000 451194000  
DT - Basic  
CT - US4416312; US4688540; US5842461  
STG - (A) United States patent  
AB - Two imaging equipment are provided at a pair of cutting blade  
units, and the two imaging equipment image patterns at first  
positions in proximity to the center of a wafer at the same time.  
A controller drives drive mechanisms to align the wafer in such a  
way that current image patterns at the first positions can match  
with a reference pattern at the first positions. Then, the two  
imaging equipment are moved to positions for imaging patterns at  
second positions at the outer circumference of the wafer to image  
the patterns at the second positions. The controller drives the  
drive mechanisms to align the wafer in such a way that current  
image patterns at the second positions can match with a reference  
pattern at the second positions.  
UP - 2000-44

1 / 1 CRXX - @CLAIMS/RRX  
PN - 6,142,138 A 20001107 [US6142138]  
PA - Kulicke & Soffa Investments Inc; Tokyo Seimitsu Co Ltd JP  
ACT - 20011003 REASSIGNED  
AGREEMENT

Assignor: TOKYO SEIMITSU CO., LTD. DATE SIGNED: 09/28/2001  
KULICKE & SOFFA INVESTMENTS, INC. DATE SIGNED: 09/06/2001

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Reel 012211/Frame 0786

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2 / 3 INPADOC - ©INPADOC  
PN - JP 11162890 A2 19990618 [JP11162890]  
TI - METHOD AND DEVICE FOR ALIGNMENT  
IN - AZUMA MASAYUKI; SHIMODA HIROSHI  
PA - TOKYO SEIMITSU CO LTD  
AP - JP 330540/97-A 19971201 [1997JP-0330540]  
PR - JP 330540/97-A 19971201 [1997JP-0330540]  
IC - H01L-021/301; H01L-021/68

3 / 3 INPADOC - ©INPADOC  
PN - US 6142138 A 20001107 [US6142138]  
TI - HIGH SPEED METHOD OF ALIGNING CUTTING LINES OF A WORKPIECE USING  
PATTERNS  
IN - AZUMA MASAYUKI [JP]; SHIMODA HIROFUMI [JP]  
PA - TOKYO SEIMITSU CO LTD [JP]; KULICKE & SOFFA INVESTMENTS [US]  
AP - US 199198/98-A 19981125 [1998US-0199198]  
PR - JP 330540/97-A 19971201 [1997JP-0330540]  
IC - B28D-001/04

Session finished: 02 DEC 2003 Time 14:51:55

QUESTEL.ORBIT thanks you. Hope to hear from you again soon.



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3	FWCLM	1
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5	DRW	7
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9	OATH	2
10	BIB	2
11	WFEE	1
12	WFEE	2
13	FRPR	25

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Remarks:

Order of re-scan issued on .....